

February 2014

FPF1203 / FPF1203L / FPF1204 / FPF12045 IntelliMAX™ Ultra-Small, Slew-Rate-Controlled Load Switch

Features

- 1.2 V to 5.5 V Input Voltage Operating Range
- Typical R_{ON}:
 - 45 mΩ at V_{IN}=5.5 V
 - 55 mΩ at V_{IN}=3.3 V
 - 90 mΩ at V_{IN}=1.8 V
 - 185 mΩ at V_{IN}=1.2 V
- Slew Rate Control with t_R:
 - FPF1203/FPF1203I/FPF1204: 100 μs
 - FPF12045: 2 μs
- Output Discharge Function on FPF1204 / 45
- Low <1.5 µA Quiescent Current
- ESD Protected: Above 7 kV HBM, 2 kV CDM
- GPIO / CMOS-Compatible Enable Circuitry
- 4-Bump, WLCSP 0.76 mm x 0.76 mm, 0.4 mm Pitch

Applications

- Mobile Devices and Smart Phones
- Portable Media Devices
- Tablet PCs
- Advanced Notebook, UMPC, MID
- Portable Medical Devices
- GPS and Navigation Equipment

Description

The FPF1203 / 03L / 04 / 45 are ultra-small integrated IntelliMAX™ load switches with integrated P-channel switch and analog control features. Integrated slew-rate control prevents inrush current and the resulting excessive voltage drop on the power rail. The input voltage range operates from 1.2 V to 5.5 V to provide power-disconnect capability for post-regulated power rails in portable and consumer products. The low shut-off current allows power designs to meet standby and off-power drain specifications.

The FPF120x are controlled by a logic input (ON pin) compatible with standard CMOS GPIO circuitry found on Field Programmable Gate Array (FPGA) embedded processors. The FPF120x are available in 0.76 mm x 0.76 mm 4-bump WLCSP.

Ordering Information

Part Number	Top Mark	Switch (Typical) at 3.3V _{IN}	Output Discharge	ON Pin Activity	t _R	Package
FPF1203UCX	QL	55 mΩ	NA	Active HIGH	100 µs	
FPF1203LUCX	QP	55 mΩ	NA	Active LOW	100 µs	
FPF1204UCX	QM	55 mΩ	65 Ω	Active HIGH	100 µs	4-Bump, Wafer-Level Chip-Scale Package (WLCSP), 0.76 mm x
FPF1204BUCX (Backside Laminate)	QM	55 mΩ	65 Ω	Active HIGH	100 µs	0.76 mm, 0.4 mm Pitch
FPF12045UCX	NC	55 mΩ	65 Ω	Active HIGH	2 µs	

Application Diagram

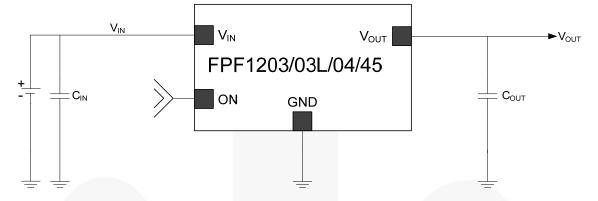


Figure 1. Typical Application

Functional Block Diagram

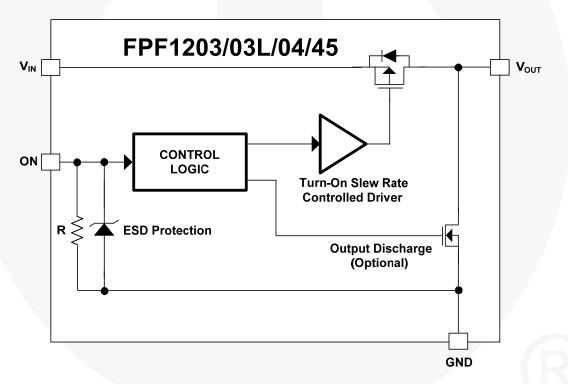


Figure 2. Functional Block Diagram (Output Discharge for FPF1204 / 45)

Pin Configurations



Figure 3. WLCSP Bumps Facing Down (Top View)

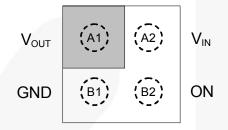


Figure 5. Pin Assignments (Top View)

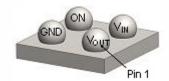


Figure 4. WLCSP Bumps Facing Up (Bottom View)

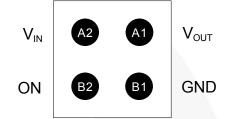


Figure 6. Pin Assignments (Bottom View)

Pin Definitions

Pin#	Name	Description	
A1	V_{OUT}	Switch output	
A2	V_{IN}	Supply input: input to the power switch	
B1	GND	bund	
B2	ON	N/OFF Control, active HIGH; FPF1203/04/45	
B2	ON	DN/OFF Control, active LOW; FPF1203L	

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Paramete	r	Min.	Max.	Unit
V _{IN}	V _{IN} , V _{OUT} , V _{ON} to GND		-0.3	6.0	V
I _{SW}	Maximum Continuous Switch Current at Am	bient Operating Temperature		2.2	Α
P _D	Power Dissipation at T _A =25°C			1.0	W
T _{STG}	Storage Temperature Range			+150	°C
0	Thormal Posistance Junation to Ambient	1S2P with One Thermal Via ⁽¹⁾		110	°C/W
Θ_{JA}	Thermal Resistance, Junction-to-Ambient	1S2P without Thermal Via ⁽²⁾		95	C/VV
ESD	Electrostatic Discharge Capability ^(1,2)	Human Body Model, JESD22-A114	7		- kV
ESD		Charged Device Model, JESD22-C101	2		

Notes:

- Measured using 2S2P JEDEC std. PCB.
- 2. Measured using 2S2P JEDEC PCB COLD PLATE Method.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{IN}	Input Voltage	1.2	5.5	V
T _A	Ambient Operating Temperature	-40	+85	°C

Electrical Characteristics

Unless otherwise noted, V_{IN} =1.2 V to 5.5 V and T_A =-40 to +85°C. Typical values are at V_{IN} =3.3 V and T_A =25°C.

Symbol	Parameter		Condition	Min.	Тур.	Max.	Unit	
Basic Op	eration			•				
V _{IN}	Supply Voltage			1.2		5.5	V	
	Off Supply FPF1203/04/45 Current FPF1203L		V _{ON} =GND, V _{OUT} =Open, V _{IN} =5.5 V 0.		0.1	1.0		
I _{Q(OFF)}			V _{ON} =V _{IN} , V _{OUT} =Open, V _{IN} =5.5 V	,	1.0	2.0	μA	
	Shutdown	FPF1203/04/45	V _{ON} =GND, V _{OUT} =GND		0.1	1.0	шА	
I_{SD}	Current	FPF1203L	V _{ON} =V _{IN} , V _{OUT} =GND		1.2	3.0	μA	
	Quiescent	FPF1203/04/45	I _{OUT} =0 mA, V _{ON=} V _{IN} , =5.5 V		0.4	4.5		
ΙQ	Current	FPF1203L	I _{OUT} =0 mA, V _{ON} =GND, V _{IN} , = 5.5 V		0.1	1.5	μA	
			V _{IN} =5.5 V, I _{OUT} =200 mA, T _A =25	°C	45	55 ⁽³⁾		
			V _{IN} =3.3 V, I _{OUT} =200 mA, T _A =25	°C	55	65 ⁽³⁾		
R_{ON}	On Resistance		V _{IN} =1.8 V, I _{OUT} =200 mA, T _A =25	°C	90	100 ⁽³⁾	$m\Omega$	
			V _{IN} =1.2 V, I _{OUT} =200 mA, T _A =25	°C	185	220 ⁽³⁾		
			V _{IN} =1.8 V, I _{OUT} =200 mA, T _A =85	°C ⁽³⁾		105		
R _{PD}	Output Discharg	e R _{PULL DOWN}	V _{IN} =3.3 V, V _{ON} =OFF, I _{FORCE} =20 mA, T _A =25°C, FPF1204 / FPF12045		65	75	Ω	
V _{IH}	On Input Logic H	HGH Voltage	V _{IN} =1.2 V to 5.5 V	1.15			V	
V _{IL}	On Input Logic L	OW Voltage	V _{IN} =1.2 V to 5.5 V			0.65	V	
R _{ON_PD}	Pull-Down Resis	stance at ON Pin	V _{IN} =1.2 V to 5.5 V		8.3		ΜΩ	
I _{ON}	On Input Leakag	је	V _{ON} =V _{IN} or GND			1	μA	
Dynamic	Characteristics							
t _{DON}	Turn-On Delay ⁽⁴)			70			
t _R	V _{OUT} Rise Time ⁽⁴	4)	V _{IN} =3.3 V, R _L =10 Ω, C _L =0.1 μF, T _A =25°C, FPF12045		100		μs	
ton	Turn-On Time ⁽⁶⁾				170			
t _{DON}	Turn-On Delay ⁽⁴)			2			
t _R	V _{OUT} Rise Time ⁽⁴	4)		/	2			
ton	Turn-On Time ⁽⁶⁾				4	У		
t _{DOFF}	Turn-Off Delay ⁽⁴	,5)			0.5			
t _F	V _{OUT} Fall Time ⁽⁴⁾		V_{IN} =3.3 V, R _L =10 Ω , C _L =0.1 μ F, T _A =25°C, FPF1203L	,	2.0		μs	
t _{OFF}	Turn-Off Time ^{(5,7}	7)	11A-25 C, FFF1203L		2.5			
t _{DOFF}	Turn-Off Delay ⁽⁴	,5)			6			
t _F	V _{OUT} Fall Time ⁽⁴⁾	5)	' _{IN} =3.3 V, R _L =500 Ω, C _L =0.1 μF,	F,	115		μs	
t _{OFF}	Turn-Off Time ^{(5,7}		T _A =25°C, FPF1203L		121			
t _{DOFF}	Turn-Off Delay ^(4,5) V _{OUT} Fall Time ^(4,5)				4.0		μs	
t _F			V_{IN} =3.3 V, R _L =10 Ω , C _L =0.1 μ F, T _A =25°C, FPF1203	,	2.9			
t _{OFF}	Turn-Off Time ^{(5,7}		1A-20 0, FPF 1200		7.3		1	
t _{DOFF}	Turn-Off Delay ⁽⁴	,5)			6		μs	
t _F	V _{OUT} Fall Time ⁽⁴⁾		V _{IN} =3.3 V, R _L =500 Ω, C _L =0.1 μI	F,	115			
toff	Turn-Off Time ^{(5,7}		T _A =25°C, FPF1203		121			

Continued on the following page...

Electrical Characteristics

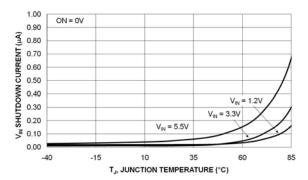
Unless otherwise noted, V_{IN} =1.2 V to 5.5 V and T_A =-40 to +85°C. Typical values are at V_{IN} =3.3 V and T_A =25°C.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
t _{DOFF}	Turn-Off Delay ^(4,5)			4.0		
t_{F}	V _{OUT} Fall Time ^(4,5)	V_{IN} =3.3 V, R _L =10 Ω, C _L =0.1 μF, T_A =25°C, FPF1204/45 ⁽⁵⁾		2.5		μs
t _{OFF}	Turn-Off Time ^(5,7)	14-23 0,111 120-743		6.5		
t _{DOFF}	Turn-Off Delay ^(4,5)			6		
t_{F}	V _{OUT} Fall Time ^(4,5)	V_{IN} =3.3 V, R_L =500 Ω , C_L =0.1 μF , T_A =25°C, $FPF1204/45^{(5)}$		11		μs
t _{OFF}	Turn-Off Time ^(5,7)	1, 25 5,		17		

Notes:

- This parameter is guaranteed by design and characterization; not production tested.
- $t_{DON}/t_{DOFF}/t_R/t_F$ are defined in Figure 23. Output discharge enabled during off-state.
- $t_{ON} = t_R + t_{DON}$
- toff=tf + tooff. 7.

Typical Performance Characteristics



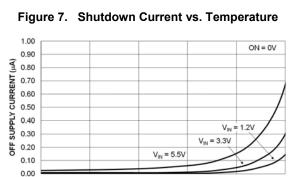


Figure 9. Off Supply Current vs. Temperature (V_{OUT} Floating)

T_J, JUNCTION TEMPERATURE (°C)

10

35

-15

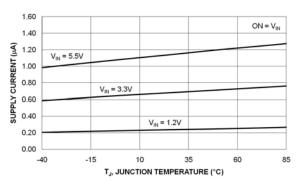


Figure 11. Quiescent Current vs. Temperature

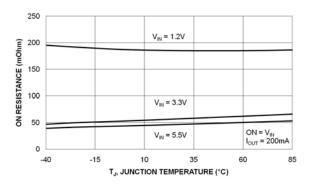


Figure 13. Ron vs. Temperature

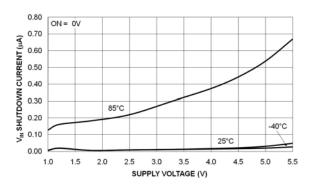


Figure 8. Shutdown Current vs. Supply Voltage

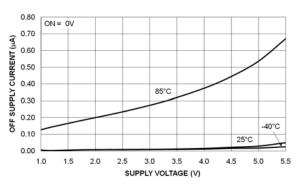


Figure 10. Off Supply Current vs. Supply Voltage (V_{OUT} Floating)

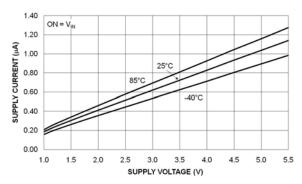


Figure 12. Quiescent Current vs. Supply Voltage

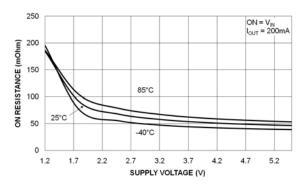
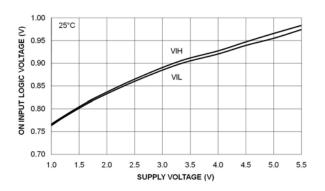


Figure 14. Ron vs. Supply Voltage

Typical Performance Characteristics (Continued)



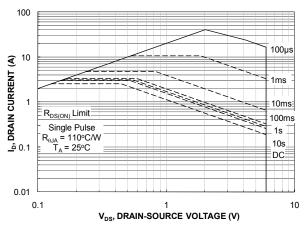


Figure 15. ON Pin Threshold vs. VIN

Figure 16. Drain Current vs. Drain-Source Voltage Safe Operating Area

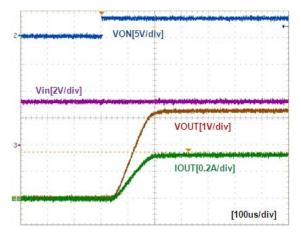


Figure 17. Turn-On Response – FPF1203 / 04 (V_{IN} =3.3 V, C_{IN} =1 μ F, C_{OUT} =0.1 μ F, R_L =10 Ω)

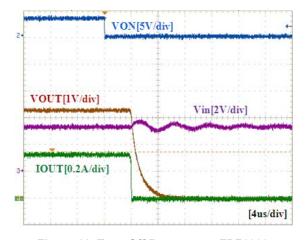


Figure 18. Turn-Off Response – FPF1203 (V_{IN} =3.3 V, C_{IN} =1 μF , C_{OUT} =0.1 μF , R_L =10 Ω)

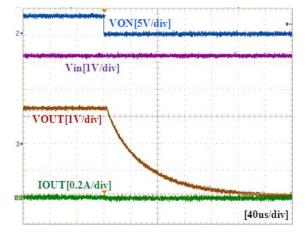
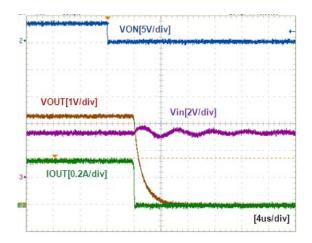


Figure 19. Turn-Off Response – FPF1203 (V_{IN} =3.3 V, C_{IN} =1 μF , C_{OUT} =0.1 μF , R_L =500 Ω)

Typical Performance Characteristics (Continued)



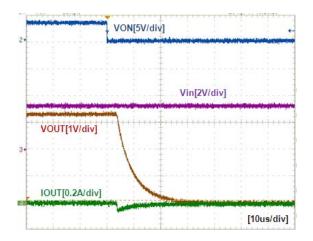


Figure 20. Turn-Off Response (V_{IN}=3.3 V, C_{IN}=1 μ F, C_{OUT}=0.1 μ F, R_L=10 Ω , FPF1204 / 45)

Figure 21. Turn-Off Response (V_{IN}=3.3 V, C_{IN}=1 μ F, C_{OUT}=0.1 μ F, R_L=500 Ω , FPF1204 / 45)

Operation and Application Description

The FPF1203 / 03L / 04 / 045 are low-R_{ON} P-channel load switches with controlled turn-on. The core of each device is a 55 m Ω P-channel MOSFET and controller capable of functioning over a wide input operating range of 1.2 to 5.5 V.

The FPF1204 / 45 contain a 65 Ω on-chip load resistor for quick output discharge when the switch is turned off.

The FPF12045 features a faster V_{OUT} Rise Time of 5 μ s.

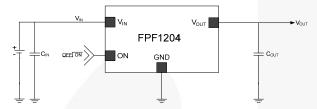


Figure 22. Typical Application

Input Capacitor

To limit the voltage drop on the input supply caused by transient inrush current when the switch turns on into a discharged load capacitor or short-circuit, a capacitor must be placed between the V_{IN} and GND pins. A 1 μF ceramic capacitor, C_{IN} , placed close to the pins is usually sufficient. Higher-value C_{IN} can be used to reduce the voltage drop in higher-current applications.

Output Capacitor

A 0.1 μ F capacitor, C_{OUT} , should be placed between the V_{OUT} and GND pins. This capacitor prevents parasitic board inductance from forcing V_{OUT} below GND when the switch is on. C_{IN} greater than C_{OUT} is highly recommended. C_{OUT} greater than C_{IN} can cause V_{OUT} to exceed V_{IN} when the system supply is removed. This could result in current flow through the body diode from V_{OUT} to V_{IN} .

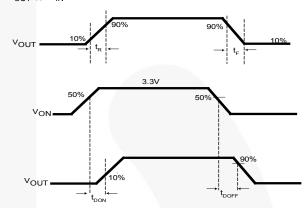
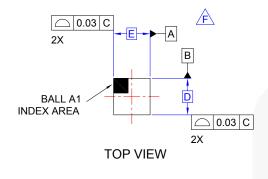


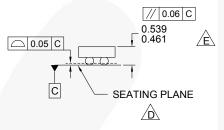
Figure 23. Timing Diagram for FPF1203/4/045

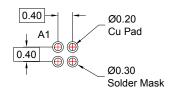
Board Layout

For best performance, traces should be as short as possible. To be most effective, input and output capacitors should be placed close to the device to minimize the effect of parasitic trace inductance on normal and short-circuit operation. Using wide traces or large copper planes for all pins (VIN, VOUT, ON, and GND) minimizes the parasitic electrical effects and the case-ambient thermal impedance. However, the VOUT pin should not connect directly to the battery source due to the discharge mechanism of the load switch.

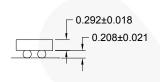
Physical Dimensions

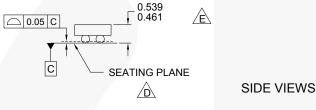






RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





В

(X)±0.018

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461-539 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILNAME: MKT-UC004AFrev1.

BOTTOM VIEW

2

0.40

0.40

Figure 24. 4-Bump, 0.76 x 0.76 mm, Wafer-Level Chip-Scale Packaging

Product Dimensions

D	E	X	Υ	
760 µm ± 30 µm	760 μm ± 30 μm	0.180 mm± 0.018 μm	0.180 mm± 0.018 μm	

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/UC/UC004AF.pdf.

⊕ 0.005∭ C A B

Ø0.260±0.020

 $(Y)\pm0.018$

F





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ F-PFS™ Svnc-Lock™ AX-CAP® FRFET® SYSTEM STERNERALS Global Power Resource BitSiC™ PowerTrench® GreenBridge™ Build it Now™ TinyBoost[®] PowerXS™ CorePLUS 11 Green FPS™ Programmable Active Droop™ TinyBuck Green FPS™ e-Series™ CorePOWER™ TinyCalc™ QFET® **CROSSVOLT** Gmax™ TinyLogic QST GTO™ TINYOPTO** Quiet Series™ Current Transfer Logic™ IntelliMAX™ TinyPower™ RapidConfigure™ DEUXPEED[®] ISOPLANAR™ TinyPWM™ Dual Cool™ Making Small Speakers Sound Louder TinyWire™ Saving our world, 1mW/W/kW at a time™ EcoSPARK® and Better™ TranSiC™ SignalWise™ EfficientMax™ MegaBuck^T TriFault Detect™ SmartMax™ TRUECURRENT®* ESBC™ MICROCOUPLER™ SMART START™ MicroFETTM μSerDes™ Solutions for Your Success™ MicroPak™ Fairchild® SPM MicroPak2™ Fairchild Semiconductor® STEALTH™ MillerDrive™ UHC FACT Quiet Series™ SuperFET[®] MotionMax™ Ultra FRFET™ FACT SuperSOT™-3 mWSaver FAST® UniFET™ SuperSOT™-6 OptoHiT¹¹ VCX™ FastvCore™ SuperSOT™-8 OPTOLOGIC® VisualMax™ FETBench™ SupreMOS[®] OPTOPLANAR® VoltagePlus™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN, NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

SyncFET™

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification		Definition		
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev. 166

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Fairchild Semiconductor: FPF1204BUCX FPF1204UCX